SDAS191A - APRIL 1982 - REVISED DECEMBER 1994

 Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

description

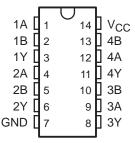
These devices contain four independent 2-input positive-AND gates. They perform the Boolean functions $Y = A \cdot B$ or $Y = \overline{A} + \overline{B}$ in positive logic.

The SN54ALS08 and SN54AS08 are characterized for operation over the full military temperature range of -55° C to 125° C. The SN74ALS08 and SN74AS08 are characterized for operation from 0° C to 70° C.

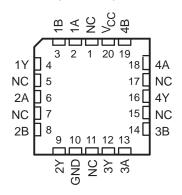
FUNCTION TABLE (each gate)

INP	UTS	OUTPUT
Α	В	Υ
Н	Н	Н
L	X	L
X	L	L

SN54ALS08, SN54AS08 . . . J PACKAGE SN74ALS08, SN74AS08 . . . D OR N PACKAGE (TOP VIEW)



SN54ALS08, SN54AS08 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

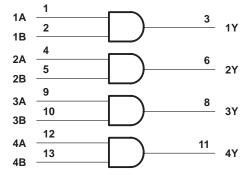
logic symbol†

1A	1	&	3	
	2	α		1Y
1B 2A	4		6	
	5		6	2Y
2B	9			
3A	10		8	3Y
3B	12			
4A 4B	13		11	4Y
4B	-			

[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for the D, J, and N packages.

logic diagram (positive logic)



SN54ALS08, SN54AS08, SN74ALS08, SN74AS08 QUADRUPLE 2-INPUT POSITIVE-AND GATES

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC}		 7 V
Input voltage, V _I		 7 V
Operating free-air temperature range, T _A :	SN54ALS08	 -55°C to 125°C
	SN74ALS08	 0°C to 70°C
Storage temperature range		_65°C to 150°C

recommended operating conditions

		SI	N54ALS0	8	SN	174ALS0	8	
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
.,	Law Israel Sanat welliams			0.8‡			0.8	
V_{IL}	Low-level input voltage			0.7§				V
ЮН	High-level output current			-0.4			-0.4	mA
loL	Low-level output current			4			8	mA
TA	Operating free-air temperature	-55		125	0		70	°C

[‡] Applies over temperature range –55°C to 70°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		TEST CONDITIONS					174ALS0	8	LINUT	
PARAMETER	TEST C						TYP¶	MAX	UNIT	
VIK	$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$			-1.5			-1.5	V	
Voн	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -0.4 \text{ mA}$	V _{CC} -2			V _{CC} -2	2		V	
V	V 45V	$I_{OL} = 4 \text{ mA}$		0.25 0.4			0.25	0.4	V	
V _{OL}	V _{CC} = 4.5 V	$I_{OL} = 8 \text{ mA}$					0.35	0.5	V	
lį	$V_{CC} = 5.5 V,$	V _I = 7 V			0.1			0.1	mA	
lН	$V_{CC} = 5.5 V,$	$V_{I} = 2.7 V$			20			20	μΑ	
IIL	V _{CC} = 5.5 V,	V _I = 0.4 V			-0.1			-0.1	mA	
IO [#]	V _{CC} = 5.5 V,	V _O = 2.25 V	-20		-112	-30		-112	mA	
ICCH	V _{CC} = 5.5 V,	V _I = 4.5 V		1.3	2.4		1.3	2.4	mA	
^I CCL	V _{CC} = 5.5 V,	V _I = 0		2.2	4		2.2	4	mA	

[¶] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

[§] Applies over temperature range 70°C to 125°C

[#] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	C _L R _L	= 50 pF = 500 S		V,	UNIT
			SN54A	LS08	SN74ALS08		
			MIN	MAX	MIN	MAX	
^t PLH	A or B	V	2	14	4	14	ne
t _{PHL}	AUIB	· '	2	12.5	3	10	ns

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V _{CC}	7 V
Input voltage, V _I	7 V
Operating free-air temperature range, T _A : SN54AS08	–55°C to 125°C
SN74AS08 .	0°C to 70°C
Storage temperature range	

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		S	N54AS0	8	S	N74AS0	3	LINIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
lOH	High-level output current			-2			-2	mA
loL	Low-level output current			20			20	mA
TA	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

242445752		TEST CONDITIONS					N74AS08	3	LINUT
PARAMETER	TEST CO	TEST CONDITIONS				MIN	TYP§	MAX	UNIT
VIK	V _{CC} = 4.5 V,	I _I = -18 mA			-1.2			-1.2	V
Voн	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -2 \text{ mA}$	V _{CC} -2			V _{CC} -2	!		V
VOL	$V_{CC} = 4.5 \text{ V},$	$I_{OL} = 20 \text{ mA}$		0.35	0.5		0.35	0.5	V
lį	$V_{CC} = 5.5 \text{ V},$	V _I = 7 V			0.1			0.1	mA
liH	$V_{CC} = 5.5 \text{ V},$	V _I = 2.7 V			20			20	μΑ
I _{IL}	$V_{CC} = 5.5 \text{ V},$	V _I = 0.4 V			-0.5			-0.5	mA
IO¶	$V_{CC} = 5.5 V,$	V _O = 2.25 V	-30		-112	-30		-112	mA
Іссн	V _{CC} = 5.5 V,	V _I = 4.5 V		5.8	9.3		5.8	9.3	mA
ICCL	$V_{CC} = 5.5 V,$	V _I = 0		14.9	24		14.9	24	mA

[§] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

SN54ALS08, SN54AS08, SN74ALS08, SN74AS08 QUADRUPLE 2-INPUT POSITIVE-AND GATES

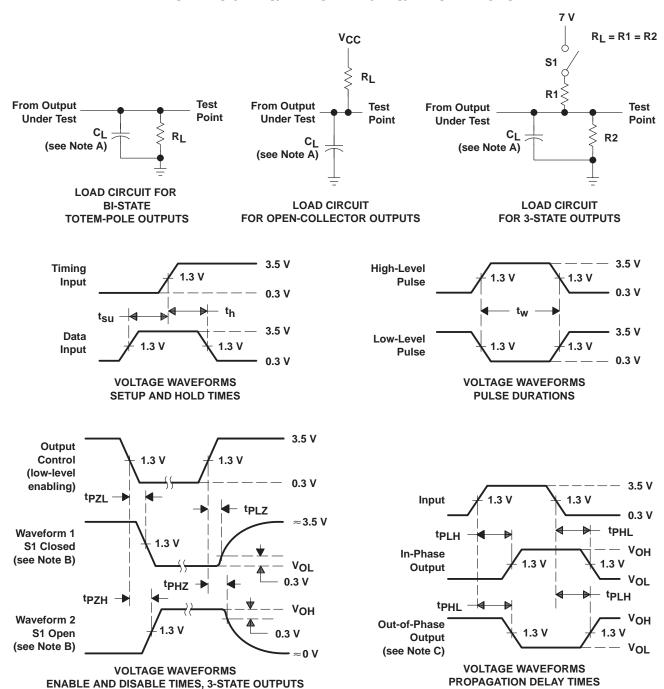
SDAS191A - APRIL 1982 - REVISED DECEMBER 1994

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$ $C_L = 50 \text{ pF},$ $R_L = 500 \Omega,$ $T_A = \text{MIN to MAX}^{\dagger}$ SN54AS08 SN74AS08				UNIT
			MIN	MAX	MIN	MAX	
^t PLH	A or B	V	1	6.5	1	5.5	ns
^t PHL	AUD	1	1	6.5	1	5.5	115

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- All input pulses have the following characteristics: PRR \leq 1 MHz, $t_r = t_f = 2$ ns, duty cycle = 50%.
- The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms







31-May-2014

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-86842012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 86842012A SNJ54ALS 08FK	Samples
5962-8684201CA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8684201CA SNJ54ALS08J	Samples
5962-8684201DA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8684201DA SNJ54ALS08W	Samples
JM38510/37401B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 37401B2A	Samples
JM38510/37401BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 37401BCA	Samples
M38510/37401B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 37401B2A	Samples
M38510/37401BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 37401BCA	Samples
SN54ALS08J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54ALS08J	Samples
SN54AS08J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54AS08J	Samples
SN74ALS08D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS08	Samples
SN74ALS08DE4	ACTIVE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70		Samples
SN74ALS08DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS08	Samples
SN74ALS08DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS08	Samples
SN74ALS08DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS08	Samples
SN74ALS08DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS08	Samples
SN74ALS08N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS08N	Samples
SN74ALS08N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		



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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74ALS08NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS08N	Samples
SN74ALS08NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS08	Samples
SN74ALS08NSRE4	ACTIVE	SO	NS	14		TBD	Call TI	Call TI	0 to 70		Samples
SN74ALS08NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS08	Samples
SN74AS08D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	AS08	Samples
SN74AS08DE4	ACTIVE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70		Samples
SN74AS08DG4	ACTIVE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70		Samples
SN74AS08DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	AS08	Samples
SN74AS08DRE4	ACTIVE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70		Sample
SN74AS08DRG4	ACTIVE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70		Samples
SN74AS08N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74AS08N	Samples
SN74AS08N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN74AS08NE4	ACTIVE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		Samples
SN74AS08NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74AS08	Samples
SN74AS08NSRE4	ACTIVE	SO	NS	14		TBD	Call TI	Call TI	0 to 70		Samples
SN74AS08NSRG4	ACTIVE	SO	NS	14		TBD	Call TI	Call TI	0 to 70		Samples
SNJ54ALS08FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 86842012A SNJ54ALS 08FK	Sample
SNJ54ALS08J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8684201CA SNJ54ALS08J	Samples
SNJ54ALS08W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8684201DA SNJ54ALS08W	Samples



PACKAGE OPTION ADDENDUM

31-May-2014

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SNJ54AS08FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54AS 08FK	Samples
SNJ54AS08J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54AS08J	Samples
SNJ54AS08W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54AS08W	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

31-May-2014

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54ALS08, SN54AS08, SN74ALS08, SN74AS08:

• Catalog: SN74ALS08, SN74AS08

Military: SN54ALS08, SN54AS08

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





		Dimension designed to accommodate the component width
E	30	Dimension designed to accommodate the component length
K	(0	Dimension designed to accommodate the component thickness
	N	Overall width of the carrier tape
F	21	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

All difficults are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS08DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74ALS08NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74AS08DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74AS08NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

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*All dimensions are nominal

7 till difficilities die Herrinian								
Device	Package Type	Package Drawing	Pins SPQ		Length (mm)	Width (mm)	Height (mm)	
SN74ALS08DR	SOIC	D	14	2500	367.0	367.0	38.0	
SN74ALS08NSR	SO	NS	14	2000	367.0	367.0	38.0	
SN74AS08DR	SOIC	D	14	2500	367.0	367.0	38.0	
SN74AS08NSR	SO	NS	14	2000	367.0	367.0	38.0	

14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14



FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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